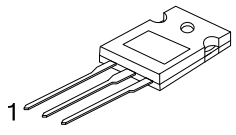
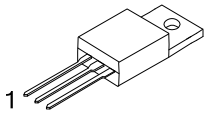
9A, 950V N-CHANNEL POWER MOSFET



TO-247



TO-230

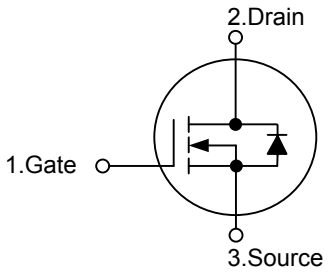
■ DESCRIPTION

The UTC **9N95** uses UTC's advanced proprietary, planar stripe, DMOS technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with low gate voltages. This device is suitable for use as a load switch or in PWM applications.

■ FEATURES

* $R_{DS(ON)}$ < 1.4 Ω @ V_{GS} = 10V, I_D = 4.5A
* Fast Switching Capability
* Avalanche Energy Specified
* Improved dv/dt Capability, High Ruggedness

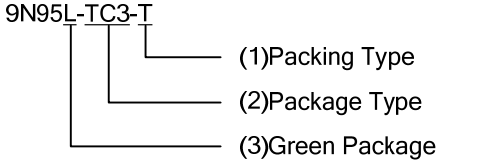
■ SYMBOL



■ ORDERING INFORMATION

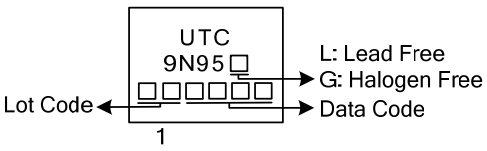
Ordering Number		Package	Pin Assignment			Packing
Lead Free	Halogen Free		1	2	3	
9N95L-TC3-T	9N95G-TC3-T	TO-230	G	D	S	Tube
9N95L-T47-T	9N95G-T47-T	TO-247	G	D	S	Tube

Note: Pin Assignment: G: Gate D: Drain S: Source



(1) T: Tube
(2) TC3: TO-230, T47: TO-247
(3) L: Lead Free, G: Halogen Free and Lead Free

■ MARKING



■ ABSOLUTE MAXIMUM RATING (T_C =25°C, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		V_{DSS}	950	V
Gate-Source Voltage		V_{GSS}	±30	V
Continuous Drain Current (T_C = 25°C)		I_D	9.0	A
Pulsed Drain Current (Note 2)		I_{DM}	36	A
Avalanche Current (Note 2)		I_{AR}	9.0	A
Avalanche Energy	Single Pulsed (Note 3)	E_{AS}	900	mJ
	Repetitive(Note 2)	E_{AR}	28	mJ
Peak Diode Recovery dv/dt (Note 4)		dv/dt	4.0	V/ns
Power Dissipation	TO-230	P_D	147	W
	TO-247		160	W
Linear Derating Factor above T_C = 25°C	TO-230		1.176	W/°C
	TO-247		1.28	W/°C
Junction Temperature		T_J	150	°C
Storage Temperature		T_{STG}	-55 ~ +150	°C

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
2. Repetitive Rating : Pulse width limited by maximum junction temperature.
3. L = 21mH, I_{AS} = 9.0A, V_{DD} = 50V, R_G = 25 Ω, Starting T_J = 25°C
4. I_{SD}≤9.0A, di/dt ≤ 200A/μs, V_{DD}≤ BV_{DSS}, Starting T_J = 25°C

■ THERMAL DATA

PARAMETER		SYMBOL	RATINGS	UNIT
Junction to Ambient	TO-230	θ_{JA}	62.5	°C/W
	TO-247		50	°C/W
Junction to Case	TO-230	θ_{JC}	0.85	°C/W
	TO-247		0.78	°C/W

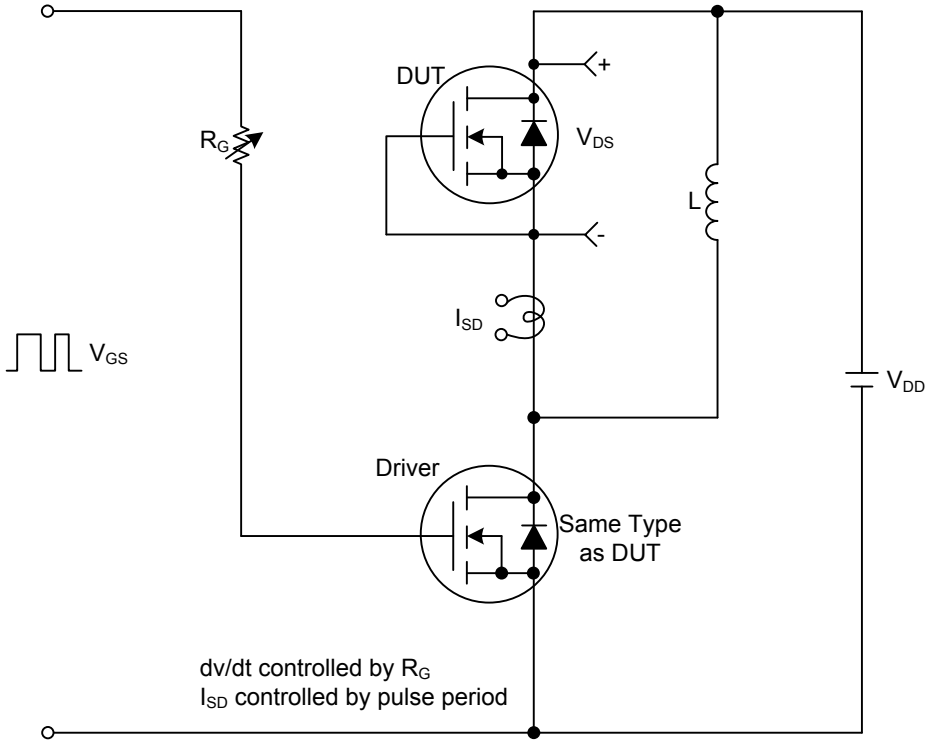
■ ELECTRICAL CHARACTERISTICS (T_J=25°C, unless otherwise specified)

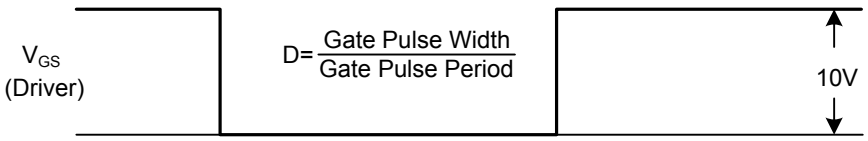
PARAMETER		SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage		BV_{DSS}	V_{GS} = 0 V, I_D = 250μA	950			V
Drain-Source Leakage Current		I_{DSS}	V_{DS} = 950 V, V_{GS} = 0 V			10	μA
Gate-Body Leakage Current	Forward	I_{GSSF}	V_{GS} = 30 V, V_{DS} = 0 V			100	nA
	Reverse	I_{GSSR}	V_{GS} = -30 V, V_{DS} = 0 V			-100	nA
Breakdown Voltage Temperature Coefficient		$\triangle BV_{DSS}/\triangle T_J$	I_D=250μA, Referenced to 25°C		0.99		V/°C
ON CHARACTERISTICS							
Gate Threshold Voltage		$V_{GS(TH)}$	V_{DS} = V_{GS}, I_D = 250μA	3.0		5.0	V
Static Drain-Source On-Resistance		$R_{DS(ON)}$	V_{GS} = 10V, I_D = 4.5A		1.05	1.4	Ω
DYNAMIC PARAMETERS							
Input Capacitance		C_{ISS}	V_{DS} = 25 V, V_{GS} = 0 V, f = 1.0 MHz		2100	2730	pF
Output Capacitance		C_{OSS}			175	230	pF
Reverse Transfer Capacitance		C_{RSS}			14	18	pF
SWITCHING CHARACTERISTICS							
Turn-On Delay Time		$t_{D(ON)}$	V_{DD} = 475V, I_D =11.0 A, R_G = 25Ω (Note 1, 2)		50	110	ns
Turn-On Rise Time		t_R			120	250	ns
Turn-Off Delay Time		$t_{D(OFF)}$			100	210	ns
Turn-Off Fall Time		t_F			75	160	ns
Total Gate Charge		Q_G	V_{DS} = 760V, I_D = 11.0A, V_{GS} = 10 V (Note 1,2)		45	58	nC
Gate-Source Charge		Q_{GS}			13		nC
Gate-Drain Charge		Q_{GD}			18		nC
DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS							
Drain-Source Diode Forward Voltage		V_{SD}	V_{GS} = 0 V, I_S = 9.0 A			1.4	V
Maximum Continuous Drain-Source Diode Forward Current		I_S				9.0	A
Maximum Pulsed Drain-Source Diode Forward Current		I_{SM}				36	A
Reverse Recovery Time		t_{rr}	V_{GS} = 0 V, I_S = 9.0 A, d_{IF} / dt =100 A/μs (Note 1)		550		ns
Reverse Recovery Charge		Q_{RR}			6.5		μC

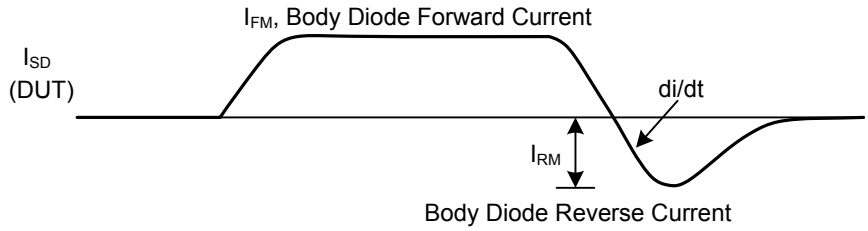
Notes: 1. Pulse Test : Pulse width≤300μs, Duty cycle≤2%.
2. Essentially independent of operating temperature.

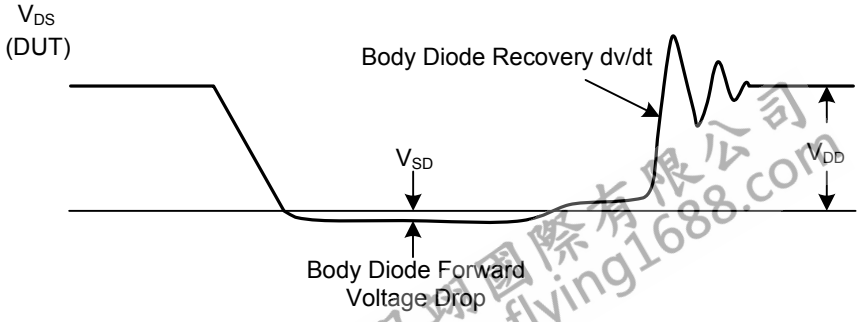
■ TEST CIRCUITS AND WAVEFORMS

Peak Diode Recovery dv/dt Test Circuit & Waveforms

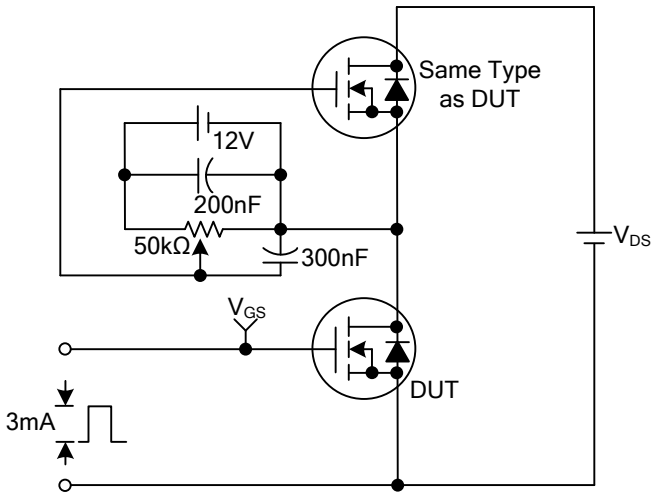




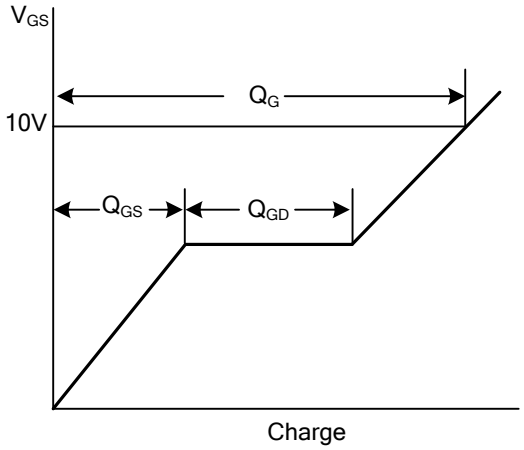




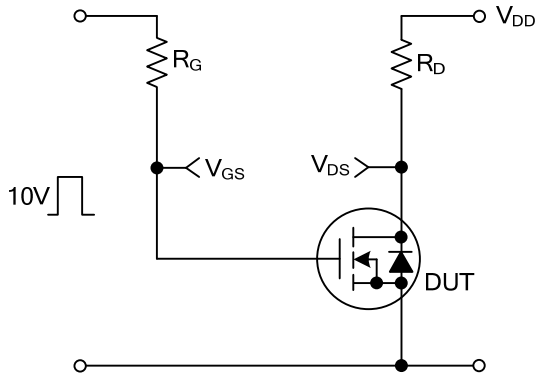
■ TEST CIRCUITS AND WAVEFORMS(Cont.)



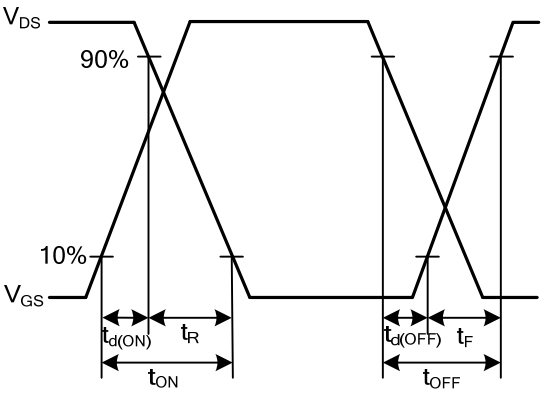
Gate Charge Test Circuit



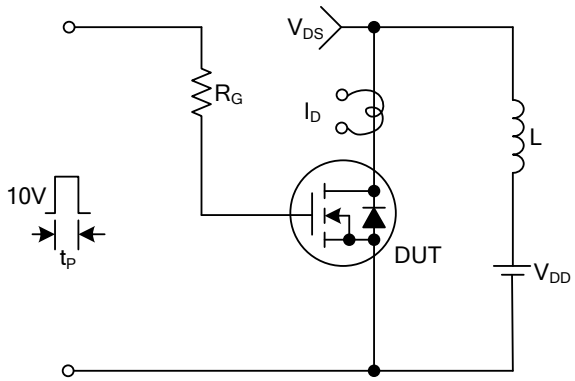
Gate Charge Waveforms



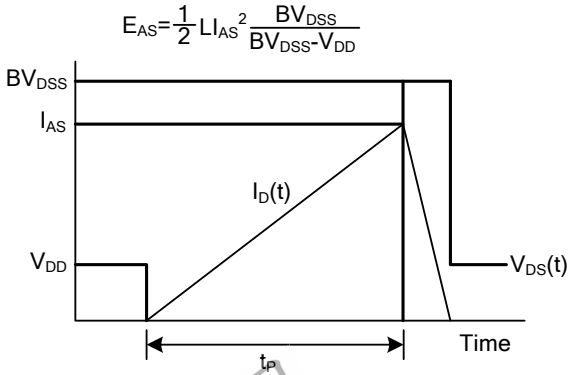
Resistive Switching Test Circuit



Resistive Switching Waveforms



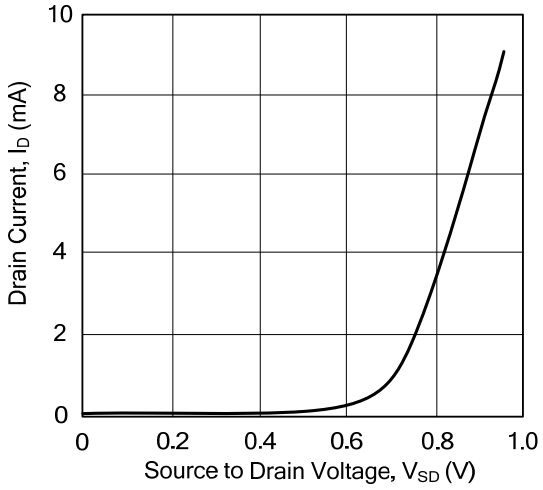
Unclamped Inductive Switching Test Circuit



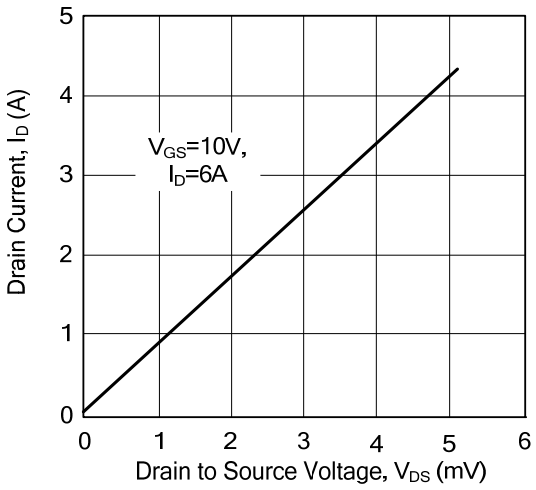
Unclamped Inductive Switching Waveforms

■ TYPICAL CHARACTERISTICS

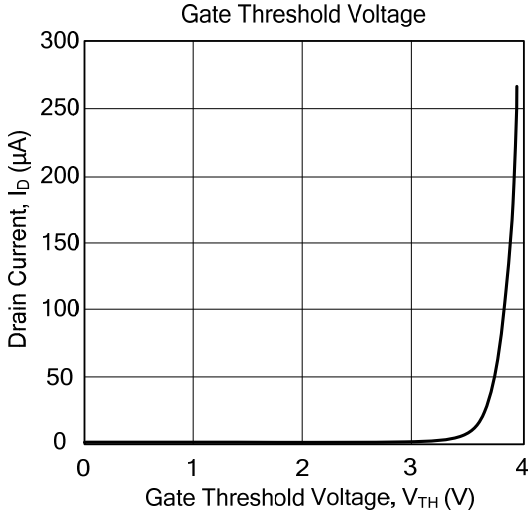
Drain Current vs.
Source to Drain Voltage



Drain-Source
On-State Resistance Characteristics



Drain Current vs.
Gate Threshold Voltage



Drain Current vs.
Drain-Source Breakdown Voltage